

Features

- Very low FOM $R_{DS(on)} \times Q_G$
- Very high commutation ruggedness

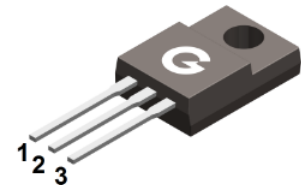
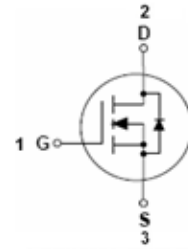
HF

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Power Factor Correction (PFC)
- Uninterruptible Power Supply (UPS)

Mechanical Data

- Case: ITO-220AB
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



ITO-220AB

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
SJ65R340F	ITO-220AB	50 pcs / Tube	SJ65R340F

Maximum Ratings (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DSS}	650	V
Gate-to-Source Voltage	V_{GSS}	± 30	V
Continuous Drain Current ($T_C = 25^\circ\text{C}$)	I_D	10	A
Continuous Drain Current ($T_C = 100^\circ\text{C}$)		6	A
Pulsed Drain Current	I_{DM}	30	A
Single Pulse Avalanche Energy ²	E_{AS}	250	mJ
Power Dissipation ($T_C = 25^\circ\text{C}$)	P_D	32	W
Operating Junction Temperature Range	T_J	-55 ~ +150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 ~ +150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	-	-	3.9	$^\circ\text{C/W}$
Thermal Resistance Junction-to-Air	$R_{\theta JA}$	-	-	62	$^\circ\text{C/W}$

Electrical Characteristics (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	650	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 650V, V_{GS} = 0V, T_J = 25^\circ\text{C}$	-	-	1	μA
		$V_{DS} = 650V, V_{GS} = 0V, T_J = 150^\circ\text{C}$	-	-	10	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS} = \pm 30V, V_{DS} = 0V$	-	-	± 100	nA
On Characteristics						
$R_{DS(ON)}$	Drain-Source On-resistance *1	$V_{GS} = 10V, I_D = 6A$	-	-	0.34	Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	-	4	V
Dynamic Characteristics						
C_{ISS}	Input Capacitance	$V_{GS} = 0V$ $V_{DS} = 100V$ $f = 250kHz$	-	781	-	pF
C_{OSS}	Output Capacitance		-	30.3	-	
C_{RSS}	Reverse Transfer Capacitance		-	1.47	-	
Switching Characteristics						
$t_{d(ON)}$	Turn-on Delay Time *3	$V_{DS} = 400V$ $V_{GS} = 13V$ $I_D = 7A$	-	6.2	-	ns
t_r	Turn-on Rise Time *3		-	21	-	
$t_{d(OFF)}$	Turn-Off Delay Time *3		-	28.8	-	
t_f	Turn-Off Fall Time *3		-	22.4	-	
Q_G	Total Gate-Charge	$V_{DS} = 400V$ $V_{GS} = 10V$ $I_D = 7A$	-	20.4	-	nC
Q_{GS}	Gate to Source Charge		-	2.77	-	
Q_{GD}	Gate to Drain (Miller) Charge		-	5.8	-	
Source-Drain Diode Characteristics						
V_{SD}	Diode Forward Voltage *1	$I_S = 6A, V_{GS} = 0V$	-	-	1.4	V
t_{rr}	Reverse Recovery Time	$I_S = 7A, V_{GS} = 0V$ $di/dt = 100 A/\mu s$	-	218	-	ns
Q_{rr}	Reverse Recovery Charge		-	1.1	-	μC

Notes:

1. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
2. The E_{AS} data shows Max. rating. The test condition is $V_{DD} = 50V, V_{GS} = 15V, L = 50mH$
3. Guaranteed by design, not subject to production

Ratings and Characteristics Curves (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

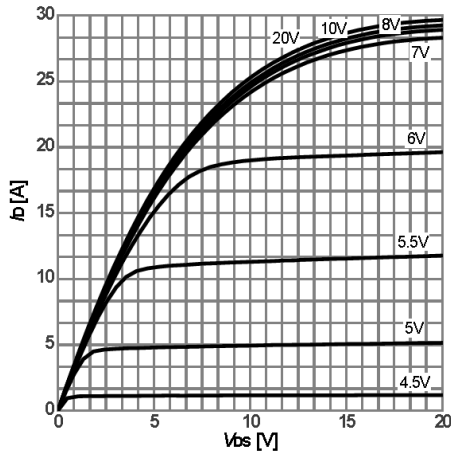


Fig 1 Output Characteristics

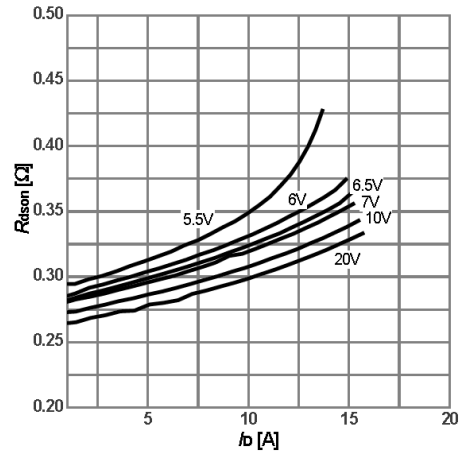


Fig 2 On-Resistance vs. Drain Current and Gate Voltage

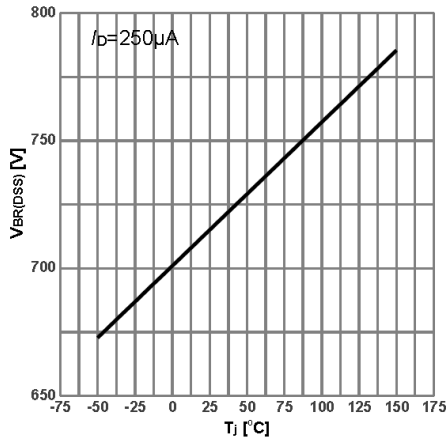


Fig 3 Breakdown Voltage vs. Junction Temperature

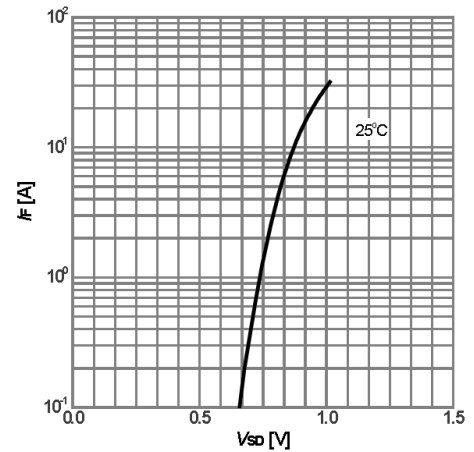


Fig 4 Body-Diode Characteristics

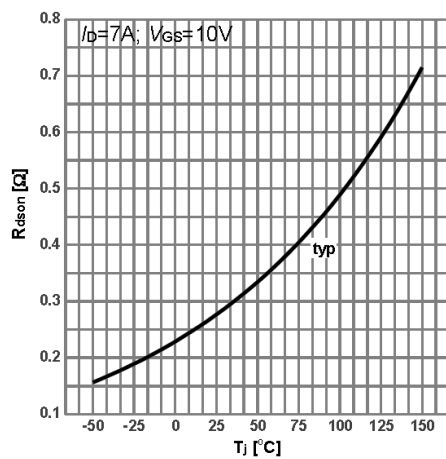


Fig 5 On-Resistance vs. Junction Temperature

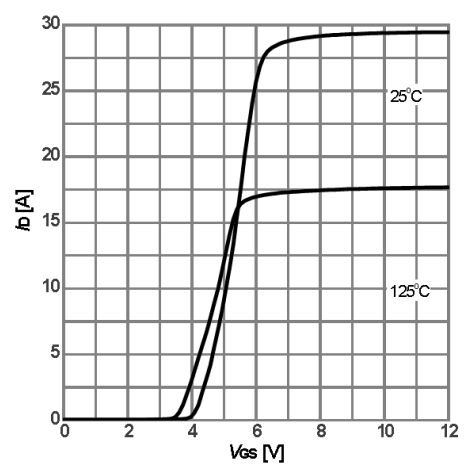


Fig 6 Transfer Characteristics

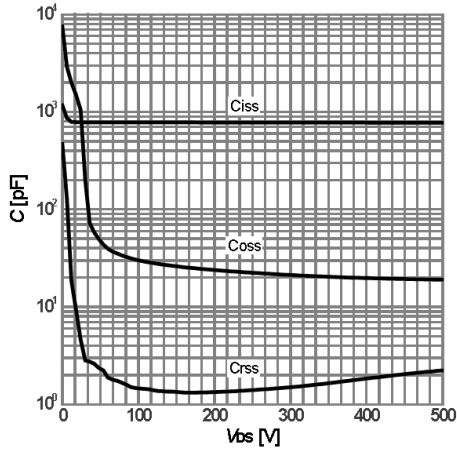


Fig 7 Capacitance Characteristics

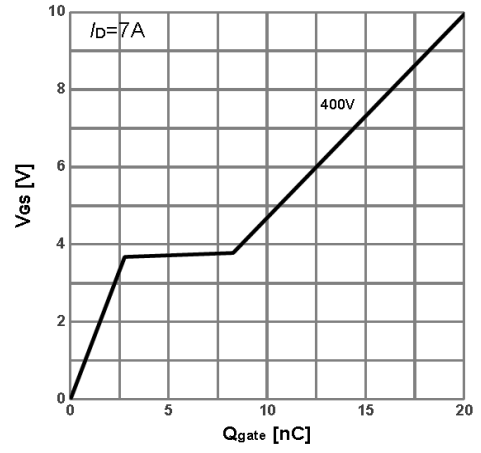


Fig 8 Gate-Charge Characteristics

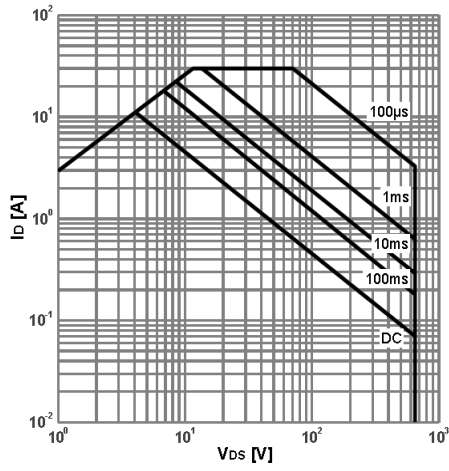


Figure 9 Maximum Safe Operating Area

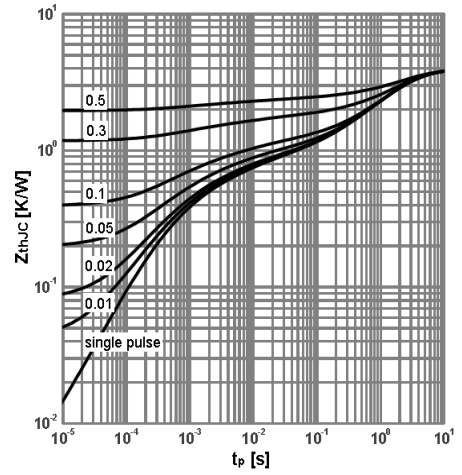
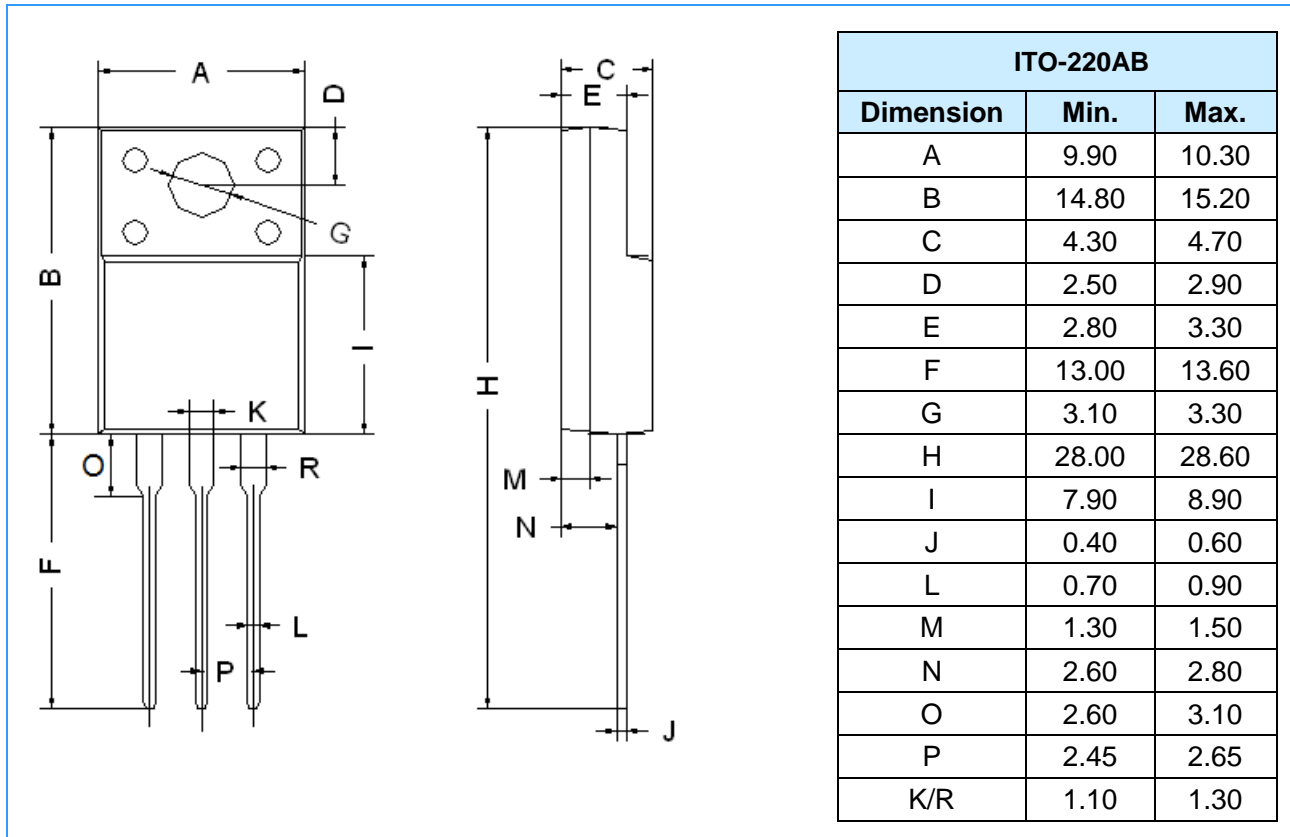


Figure 10 Max. transient thermal impedance

Package Outline Dimensions (Unit: mm)



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